

Claims

1. A heat sink assembly for removing heat from a semiconductor integrated circuit used in an electronic equipment apparatus, comprising:

a heat sink member having a body portion and a mounting portion and attachable to the semiconductor integrated circuit; and

a resilient mounting assembly positioned on the mounting portion of the heat sink member and arranged to permit the heat sink to be removably mounted on a mounting member which in turn is attachable to or part of a chassis portion of the electronic equipment apparatus, wherein the mounting portion includes means for holding the heat sink member to the mounting member when the heat sink assembly is operatively positioned on the mounting member.

2. The assembly of claim 1, wherein the holding means includes a spring element and wherein there is no direct attachment between the heat sink assembly and the mounting member.

3. The assembly of claim 1, wherein the mounting portion includes a base member and an upper member which extends upwardly from the base member, the upper member having a slightly smaller cross-section than the base member, and wherein the mounting portion further includes an angled washer positioned on the base member, a spring element mounted about the upper member above the washer, and a retainer element positioned above the spring element to hold the spring element on the upper member, and wherein in use the mounting member fits between the washer and the body portion of the heat sink member, and wherein the spring element in action tends to hold the heat sink assembly and the mounting member together in a low thermal resistance arrangement.